

## © EPODOC / EPO

PN - JP51018245 A 19760213  
 PNFP - JP54008458B B 19790416  
       - JP976727C C 19791030  
 FI - B23K35/363&A; B23K35/363&C; H05K3/34&503Z  
 FT - 5E319/AC01; 5E319/CC23; 5E319/CD01; 5E319/CD21; 5E319/CD52; 5E319/GG20  
 PA - (A)  
       TAMURA KAKEN CO LTD  
 IN - (A)  
       NAKAMURA KOZO  
 AP - JP19740089115 19740805  
 PR - JP19740089115 19740805  
 DT - I

## © WPI / Thomson

AN - 1976-23519X [13]  
 TI - Delustering [ ] for soldering printed circuits - contains inorg oxide powder and/or org acid metal salt powder  
 AB - An inorg. oxide fine powder and/or org. acid metal salt fine powder is/are added to a flux base consisting of rosin type resin, activator and org. solvent. The inorg. oxide may be silicic acid anhydride, clay, titanium oxide, silica gel, etc. and the org. acid metal salt may be aluminium stearate, aluminium oleate, aluminium palmitate, etc. The surface of the welded areas is delustered and non-corrosive.  
 IW - DELUSTERED FLUX SOLDER PRINT CIRCUIT CONTAIN OXIDE POWDER ACID METAL SALT  
 PN - JP51018245 A 19760213 DW197613  
       JP54008458B B 19790416 DW197919  
 ICAI - B23K35/362; B23K35/363; H05K3/34  
 ICCI - B23K35/362; H05K3/34  
 MC - L03-D03F L03-H04E  
 DC - L03 M23  
       - P55  
       - V04  
 PA - (TAMU-N) TAMURA KAKEN CO LTD  
 AP - JP19740089115 19740805